

Application Serial No: 10/598,903
Responsive to the *Ex Parte Quayle* Office Action mailed on: March 6, 2009

IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A driver module structure comprising:
 - a flexible circuit board provided with a wiring pattern;
 - a semiconductor device mounted on the flexible circuit board; and
 - an electrically conductive heat-radiating member joined to the semiconductor device,

wherein the wiring pattern comprises a ground wiring pattern, the flexible circuit board has a cavity that exposes a portion of the ground wiring pattern, the exposed portion of the ground wiring pattern and the heat-radiating member are connected to establish electrical continuity via a member that is fitted into the cavity, and

the cavity is a through hole penetrating the ground wiring pattern, a portion of the ground wiring pattern on an opposite side from the heat-radiating member is exposed, and the member fitted into the cavity is an electrically conductive screw that fastens the flexible circuit board and the heat-radiating member and provides electrical continuity between the exposed portion of the ground wiring pattern and the heat-radiating member.
- 2-7. (Cancelled)
8. (Previously Presented) The driver module structure according to claim 1, wherein the exposed portion of the ground wiring pattern and the screw are connected via an electrically conductive bonding material.